



PATENT

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Kie Y. Ahn and Leonard Forbes

Attorney Docket No.: 500466.04

Patent No.: US 6,953,375 B2

Serial No. : 10/813,204

Issue Date: October 11, 2005

Filed : March 29, 2004

Title : MANUFACTURING METHOD OF A FIELD EMISSION DISPLAY HAVING

POROUS SILICON DIOXIDE INSULATING LAYER

REQUEST FOR CERTIFICATE OF CORRECTION

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 Certificate

OCTO 6 2006

Of Correction

Sir:

A Certificate of Correction under 35 U.S.C. § 254 is respectfully requested for the above-identified patent in order to correct Patent and Trademark Office errors made during the printing of the patent. The changes in the patent needed to correct the errors are as follows:

Column, Line	Reads	Should Read
Item (56), Other Publications, Stevenson Reference	"of SiO ₂ , Films Over"	of SiO ₂ Films Over
Item (56), Other	"technical digest of IEDM	Technical Digest of IEDM 91,
Publications, Vaudaine Reference	91,"	
Column 4, Line 32	"FIG. 3), having a"	FIG. 3) having a

Column 5, Line 18	"ca. 10 ²⁻¹⁰³ "	ca. 10^2 - 10^3
Column 6, Line 35	"Mater. Sci. 32, (1997),"	Mater. Sci. 32 (1997),
Column 7, Line 23	"69(7), (1996),"	69(7) (1996)
Column 7, Line 38	"Silicon at low"	Silicon at Low
Column 7, Line 53	"Part 1, Vol. 36,"	Part I, Vol. 36,
Column 9, Lines 24- 25	"comprises chemical- mechanical polishing the porous"	comprises chemical-mechanical polishing of the porous
Column 10, Lines 26-27	"comprises chemical- mechanical polishing the porous"	comprises chemical-mechanical polishing of the porous
Column 10, Line 41	"act of fanning"	act of forming
Column 12, Lines	"comprises chemical- mechanical polishing the"	comprises chemical-mechanical polishing of the

The above errors for which correction is requested under 35 U.S.C. § 254 were made in the printing of the patent or in the original application. The errors are considered sufficiently important to justify the processing of a Certificate of Correction under 35 U.S.C. § 254. A Form PTO-1050, in duplicate, is enclosed herewith.

The Commissioner is hereby authorized to charge payment of any fees associated with this communication to Deposit Account No. 50-1266. A duplicate copy of this sheet is enclosed.

Favorable consideration of this Request is respectfully requested.

By:

Respectfully submitted,

Date: Lept. 21, 2006

Edward W. Bulchis, Reg. No. 26,847

Customer No. 27,076 Dorsey & Whitney LLP 1420 Fifth Avenue, Suite 3400 Seattle, WA 98101 (206) 903-8785

Attorney for Applicant(s)

EWB:tdp

Enclosures:

Postcard

Form PTO-1050 (+ copy)

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UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

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US 6,953,375 B2

DATED

October 11, 2005

INVENTOR(S)

Kie Y. Ahn and Leonard Forbes

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		the

MAILING ADDRESS OF SENDER:

Patent No. US 6,953,375 B2

DORSEY & WHITNEY LLP 1420 Fifth Avenue, Suite 3400 Seattle, Washington 98101 No. add'l. copies @ .30 per page

FORM PTO-1050 (REV. 3-82)





I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

September 25, 2006

Alexandra Beggs

Date

Title

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Applicants: Kie Y. Ahn and Leonard Forbes

Attorney Docket No.: 500466.04

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Edward W. Bulchis, Reg. No. 26,847

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